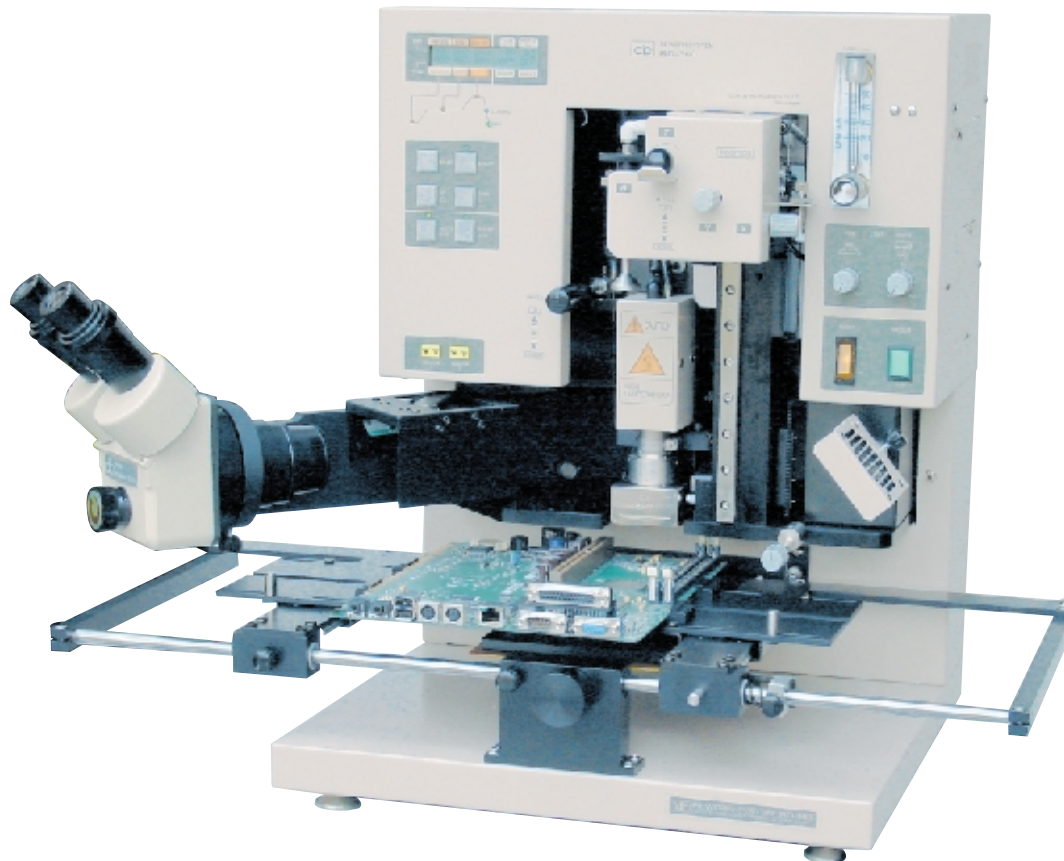


DEN-ON REWORK SYSTEM

RD-300

Placement & Removal of BGA,
 μ BGA, CSP, QFP and other Chips

**Accurate Positioning with Sharp, Highly Defined Optics.
Easy Temperature Profiling with Memory Function.**



SUMMARY

The RD-300 is a single axis placement and reflow rework station designed for both Area Array and standard leaded SMD components. The optics allow for accurate placement with a high-resolution microscope and dual prism system with excellent color clarity. This was designed to place the smallest of Area Array components like CSP and flip chips. The reflow controller uses an infrared bottom heater and a hot air top heater to precisely reflow the target component safely and accurately. It also has a large memory to store up to 40 different profiles with two of these already loaded in the system. These combined features plus a competitive price make the RD-300 an ideal machine for either users beginning to implement Area Array components on their printed circuit boards or those with growing

FEATURES

- The setting of the temperature profile can easily be done with the push button panel. The profile is shown in the LCD display panel.
- The reflow process is shown with the indicator lamp so that the real reflow is easily confirmed.
- The placement of the small sized SMT parts can be secured with the microscope.
- An affordable heater and a specially structured nozzle are incorporated to insure uniform temperature distribution.
- The infrared heater with wide heating area is incorporated in the preheater to protect the coplanarity of PCB and enhance the reflow of BGAs.
- The air pump and the vacuum pump are self-contained in the unit.

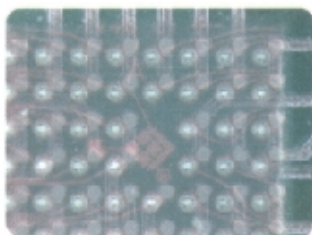
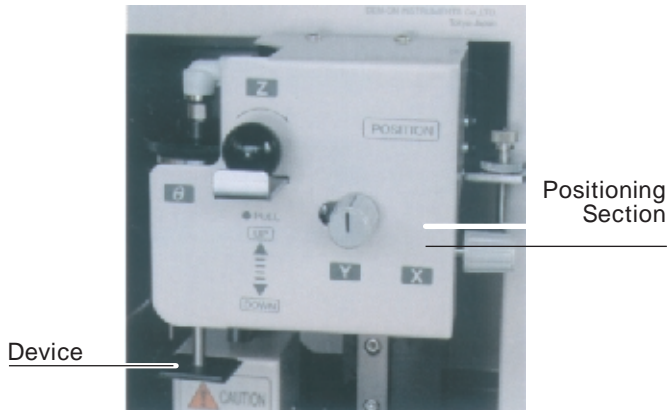


DEN-ON INSTRUMENTS CO., LTD.
DIC TRADING CO., LTD.
TOKYO JAPAN

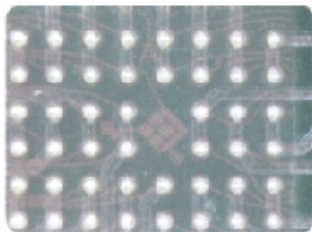
MBR ELECTRONICS GmbH, CH-8636 Wald, Switzerland
www.mbr.ch - info@mbr.ch - Tel: +41(0)55-246 24 00

PLACEMENT

The PCB pattern is overlaid with the device by adjusting x,y & .



Before alignment



After alignment

NOZZLES



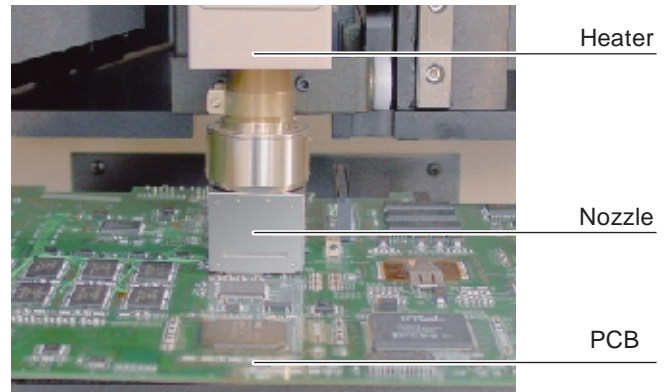
Inside Dimensions (mm)	Part Number
9 x 9	PNZ-9
11 x 11	PNZ-11
13 x 13	PNZ-13
15 x 15	PNZ-15
17 x 17	PNZ-17
21 x 21	PNZ-21
25 x 25	PNZ-25
30 x 30	PNZ-30
35 x 35	PNZ-35
40 x 40	PNZ-40
44 x 44	PNZ-44

Custom nozzles available upon request.

Specifications, designs and prices are subject to change without notice.

REFLOW

The reflow of the BGA is achieved with hot air channeled through a special nozzle. The profile is controlled internally and is set by the user for the specific board and component. The RD-300 comes standard with two set profiles and can hold up to 38 user-defined profiles.



SPECIFICATIONS

Top Heater	Hot air system with 700 watt closed loop heater.
Bottom Heater	Infrared 450 watt plate heater.
Maximum Device Size	27 x 27 mm utilizing full field of vision 50 x 50 mm shifting microscope viewing corners
Maximum PCB Size	280 x 450 mm
Air Flow	23 liters per minute
Power Requirements	100-120VAC, 12.5 amps
Dimensions	400W x 518H x 370D mm
Weight	25 kg.

OPTIONS

- Optics Alignment Kit
- Component Stenciling Kits
- Flux Applicator Block



BP-200H



SP-100

Component Stenciling Kits are available for most components. Please contact Denon or the nearest authorized Denon distributor to check for availability.



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